Overview

HP Engage One G2 All-In-One system

FRONT VIEW

Overview

HP Engage One G2 All-In-One system

REAR VIEW

HP Engage One G2 Advanced Hub

1. RJ-45 NIC (network) jack
2. USB Type-C power delivery port (36 W, 5V/9V/ 12V@3A) with Alternate Mode (downstream)
3. 4x USB 3.2 G1 (5V@900mA)
4. 2x COM Port power serials (5V/12V@1A)
5. USB Type-C port with power delivery (upstream) (100 W)
6. DC IN connector (280W Adaptor Power Connector)
7. 2x Powered USB 2.0 12V ports
8. Powered USB 2.0 24V port
9. RJ-12 (cash drawer) jack

STAND CONFIGURATIONS

HP Engage One G2 VESA Mount (100x100mm)

* 1 USB Type-C 10Gbps UFP 100W for power cord or to connect USB-C to Advanced Hub

HP Engage One G2 counter mount

HP Engage One G2 AiO Swivel Stand

Overview

AT A GLANCE

Color: Ebony Black

Optional Integrated Peripherals: camera, NFC, MSR

IP 54 Rating

Orientation: Landscape

Display:

- 15.6" diagonal, FHD (1920 x 1080), touch, IPS, UWVA, anti-glare, 350 nits, 45% NTSC

Processor choices:

- Intel® Core™ 5 processor
- Intel® Core™ 3 processor
- Intel® Processor U300E

Graphics:

- Intel® UHD Graphics for RPL-U i5/i3/ Pentium GT2

Intel® Wi-Fi 7 BE200 (2x2) and Bluetooth® 5.4 wireless card, non-vPro®

2 DDR5 Memory Slots (32 GB Maximum)

2 M.2 slots for SSD

256 GB PCIe® NVMe™ SSD

512 GB PCIe® NVMe™ SSD

Operating System choices:

- Windows 11 Pro 64-bit[1]
- Windows 11 IoT Enterprise 2024 LTSC
- ChromeOS Flex
- FreeDOS 3.0
- SUSE Linux® Enterprise Desktop 15 (certification only)

Stands:

- HP Engage One G2 Stand
- HP Engage One G2 Swivel Stand (Available in August)
- Connectivity Base & VESA Mount

HP Engage One G2 VESA Mount

- 1 USB Type-C 10Gbps UFP PD 100W Input

HP Engage One G2 Advanced hub

- 1 RJ 45 NIC, 1 RJ 12 cash drawer connector,
- 2 COM Port power serials (5V/12V@1A)
- 4 USB-A 3.2 G1
- 1 DC IN connector
- 1 USB-CDFP (PD 36 W Output Alt Mode DisplayPort™)
- 1 USB-C UFP (PD 100W Output data port]
- 2 P-USB 2.0 12V
- 1x P-USB 2.0 24V

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

Preinstalled	Windows 11 Pro 64-bit1 Windows 11 IoT Enterprise 2024 ChromeOS Flex FreeDOS 3.0
Certified	SUSE Linux® Enterprise Desktop 15[2]

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Certification on a single platform configuration. More information about SUSE: https://www.suse.com/partners/ihv/yes/

The following features are not supported by SUSE Linux Enterprise Desktop:

- Power Management features
- Multi-touch capabilities
- Systems configured with Linux do not qualify for ENERGY STAR®

Features

ADAPTERS AND CABLES

HP USB-C® to DisplayPort
HP USB-C® to HDMI
HP USB-C® to VGA
USB to Serial Port Adapter

NETWORKING/COMMUNICATIONS

Intel® Wi-Fi 7 BE200 and Bluetooth® 5.4 wireless card (2x2 non-vPro, supporting gigabit data rate)[1].

1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires compatible Windows 11 OS, compatible processor, and separately purchased Wi-Fi 7 router to support backwards compatibility with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported.

Near field communication

NFC Mirage WNC XRAV-1

PORTS

HP Engage One G2 Head unit I/O:
1x USB-C PD up to 27W (12V+- 5% 2A / 9V+- 5% 3A / 5V+- 5% @3A) with alternative mode.[1]
1x UAJ (Audio jack)
Note: Internal access door for the SSD

HP Engage One G2 Advanced hub I/O
1x RJ12 Cash Drawer
2x 12V P-USB 2.0
1x 24V P-USB 2.0
2x COM port power serial 5V/12V @1A
4x USB3.2 G1 Type A/900mA
1x RJ 45 NIC
1x DC connector
1x USB3.2 G2 Type-C® DP Alt Mode / 36W[2]
1x USB Type-C port with power delivery (upstream) (100 W)

HP Engage One G2 VESA Mount
1 USB-C UFP PD 100W[3]

1. HP 100W port only compatible with the 100W cable included with the product. Cable required for the HP Engage One Pro to operate.
2. Limit to gen1 speeds due to USB cable.
3. VESA Mount USB-C compatible with system 100W USB-C power adapter to power head unit only or to attach Advanced Hub

Features

USB SPECIFICATION

Speed	Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1

SOFTWARE COMPONENTS AND APPLICATIONS

BIOS

HP BIOSphere Gen6[1]
HP Secure Erase[2]
Device Guard Enablement

HP BIOS Additional Features

Power-On password

Software

HP Privacy Settings
HP Setup Integrated OOBE
HP Notifications
myHP

Manageability Features

HP Driver Packs
HP Manageability Integration Kit[3]
HP Image Assistant
HP Smart Support[4]

Security Management

HP Client Security Manager Gen7[5]
HP Multi-Factor Authenticate
HP SpareKey
HP Sure Start[6]
HP Sure Run[7]
HP Sure Recover[7, 8]

Security Features

Bolt to counter mechanism
VESA mounting
Keyed Cable Lock
Trusted Platform Module TPM 2.0
Drive lock
USB enable/disable (via BIOS)
Power-on password (via BIOS)
Setup password (via BIOS)

Features

1. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
2. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
3. HP Manageability Integration Kit requires Windows 10 or Windows 11 and can be downloaded from http://www.hp.com/go/clientmanagement.
4. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.
5. HP Client Security Manager Gen7 requires Windows.
6. HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 Pro and higher.
7. HP Sure Run & Sure Recover is supported on Win 10 Pro & Win 10 IoT Enterprise 2019 LTSC and above; but not on Win 10 IoT Enterprise 2016 LTSB. See product specifications for availability, not available on all products.
8. HP Sure Recover Gen3 is available on selected HP PCs and requires an open network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. See product specifications for availability, not available on all products.

Features

PROCESSORS

Intel® Core™ 5 processor 120U (12M Cache, up to 5.00 GHz)
Intel® Core™ 3 processor 100U (10M Cache, up to 4.70 GHz)
Intel® Processor U300EE (8M Cache, up to 4.30 GHz)

Processors family

Intel ® Core™ processors (Series 1) Core 5 processor
Intel ® Core™ processors (Series 1) Core 3 processor
Intel ® Processor U-series

NOTE: Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a configuration surement of higher performance.
NOTE:. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://http://www.intel.com/technology/turboboost for more information.

The HP Engage One G2 AiO System Retail System features this technology and includes processors that are part of the Intel® Stable Image. Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP Engage One G2 AiO System Retail System.

Technical Specifications – Operator Display

OPERATOR DISPLAY*

15.6" Diagonal Wide Aspect, Projective Capacitive, Anti-glare, Anti-smudge, IPS Display	
Touch Technology	10 touch-points Projected Capacitive Touchscreen
Resolution	1920 x 1080
Aspect Ratio	16:9
Max Color	16.7M
Brightness	Typical 350 Nits*
Contrast Ratio	Typical 1000:1
Pixel Pitch	0.17925 x 0.17925mm
Viewing Angle	Horizontal 178º, Vertical 178º
Response rate	25ms (Typical On / Off)
Backlight	LED
Operating Temperature range	0 to 40ºC (+ 40ºC as panel surface temperature)

***NOTE:** Nits is the measure of the typical brightness of the panel as specified, prior to anti-glare coating. All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

MEMORY

Memory Type

	Maximum	# of Slots
DDR5 5600 Transfer rates up to 5600 MT/s	32GB	2 SODIMM

Memory Upgrades

8GB (1x8GB) DDR5 5600 SODIMM Memory
16GB (2x8GB) DDR5 5600 SODIMM Memory
16GB (1x16GB) DDR5 5600 SODIMM Memory
32GB (2x16GB) DDR5 5600 SODIMM Memory

Note: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system. Memory modules support data transfer rates up to 2400 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

CAUTION: You must shut down the Retail System and disconnect the power cord before adding or removing memory modules. Regardless of the power-on state, voltage is always supplied to the memory modules as long as the Retail System is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

Technical Specifications – Storage

STORAGE

Solid State Drives (SSD)

Drive Bays

(2) M.2 PCIe x4 2280/2230 Combo (for storage)

PCIe NMVe Solid State Drives (SSD)[1]

256GB M.2 2280 PCIe NVMe SED OPAL2 Value Solid State Drive
256GB M.2 2280 PCIe Value NVMe Solid State Drive
512GB M.2 2280 PCIe NVMe Value Solid State Drive

Storage accelerator

NVMe RAID[1]

1. Storage DriveLock does not work with Self-Encrypting or Optane based storage

256 GB M.2 2280 PCIe NVMe SSD

Unformatted Capacity	256GB
Interface	PCIe
Form Factor	M.2
Height	2.30mm
Width	22mm
Length	80mm
Weight	10 g (00.2 lb)
Maximum Sequential Read	Up to 3100MB/s
Maximum Sequential Write	Up to1200MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 40°C (32° to 104°F) [ambient temp]
Features	Pyrite 2.0; TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe Value SSD

Unformatted Capacity	512GB
Interface	PCIe
Form Factor	M.2
Height	2.30mm
Width	22mm
Length	80mm
Weight	10 g (00.2 lb)
Maximum Sequential Read	Up to 3500MB/s
Maximum Sequential Write	Up to 1600MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 40°C (32° to 104°F) [ambient temp]
Features	Pyrite 2.0; TRIM; L1.2

256GB PCIe 2280 NVMe Self Encrypted OPAL2 Value SSD

Unformatted Capacity	256 GB
Interface	PCIe
Form Factor	M.2
Height	2.30mm
Width	22mm
Length	2.8mm
Weight	10 g (00.2 lb)
Maximum Sequential Read	Up to 3100MB/s
Maximum Sequential Write	Up to 1200MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 40°C (32° to 104°F) [ambient temp]
Features	Opal 2.0; TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

NETWORKING

Ethernet (RJ-45)

Realtek RTL8153CH 10/100/1000 Integrated NIC

Wireless

Intel® Wi-Fi 7 BE200 and Bluetooth® 5.4 wireless card (2x2, non-vPro, supporting gigabit data rate)[1]
MediaTek MT7925 Wi-Fi 7 + Bluetooth® 6.0 (802.11be 2x2)

NFC Mirage WNC XRAV-1	
Dimensions (L x W x H)	17.00 x 10.00 x 2.00 mm (0.67 x 0.39 x 0.08 inch)
Chipset	NPC300
System Interface	I2C
NFC RF Standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
NFC Forum Support	Type 1, Type 2, Type 3 / Type 4 NFCIP-1 / NFCIP-2
Reader Mode (PCD-VCD)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz
Card Emulation Mode (PICC-VICC)	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
Frequency	13.56 MHz
NFC Modes Supported	Reader/Writer, Peer-to-Peer

Technical Specifications – Networking

Raw RF Data Rates	106 kbps, 212 kbps, 424 kbps, 848 kbps
Operating Temperature	0°C to 40°C (32°F to 104°F)
Storage Temperature	-20°C to 125°C (-4°F to 257°F)
Humidity	Operating: 10 - 90% Non-Operating: 5 - 95%
Supply Operating Voltage	4.35 to 5.25 Volts
I/O Voltage	1.8V or 3.3V
Power Consumption	Booster enable, VBAT= 3.3V, VCC_BOOST = 5V
Mode	Power Consumption, Typical
Polling	7.3 mA
Detected Test Tag Type 1	Total 283.8 mA Net Module 236.8 mA
Detected Test Tag Type 2	Total 288.8 mA Net Module 241.8 mA
Detected Test Tag Type 3	Total 287.7 mA Net Module 240.7 mA
Detected Test Tag Type 4	Total 282.3 mA Net Module 235.3 mA
Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

Realtek RTL8153CH 10/100/1000 Integrated NIC[1]	
Connector	RJ-45
System Interface	USB
Data rates supported[2]	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/sv
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Jumbo Frame 9K

Technical Specifications – Networking

Power consumption	Cable Disconnection: 25 mW 100Mbps Full Run: 450 mW 1000Mbps Full Run: 1000 mW WoL Enable(S3/S4/S5): 50 mW WoL Disable(S3/S4/S5): 25 mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumptionACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Intel BE200 Wi-Fi 7 +Bluetooth® 5.4 Wireless Card M.2 320MHz PCIe World-wide WLAN non-vPro[1]	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11be IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n/ax/be ▪ 2.402 – 2.482 GHz 802.11a/n/ac/ax/be ▪ 4.9 – 4.95 GHz (Japan) ▪ 5.15 – 5.25 GHz

	▪ 5.25 – 5.35 GHz ▪ 5.47 – 5.725 GHz ▪ 5.825 – 5.850 GHz ▪ 5.955 – 6.415 GHz ▪ 6.435 – 6.515 GHz ▪ 6.535 – 6.875 GHz ▪ 6.895 – 7.115 GHz
Data Rates	▪ 802.11b: 1, 2, 5.5, 11 Mbps ▪ 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps ▪ 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps ▪ 802.11n: max 300Mbps ▪ 802.11ac: 1733Mbps ▪ 802.11ax: max 2.4Gbps ▪ 802.11be: max 5.76Gbps
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM, 4096QAM
Security	▪ IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only ▪ AES-CCMP: 128 bit in hardware ▪ 802.1x authentication ▪ WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. ▪ WPA2 certification ▪ WPA3 certification ▪ IEEE 802.11i ▪ WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power	▪ 802.11b, 1Mbps: +17dBm minimum ▪ 802.11g, 6Mpbs: +16dBm minimum ▪ 802.11a, 6Mbps: +17dBm minimum ▪ 802.11n, MCS7(HT20): +14dBm minimum ▪ 802.11n, MCS7(HT40): +13.5dBm minimu ▪ 802.11ac MCS9(VHT20): 13.5dBm minimum ▪ 802.11ac MCS9(VHT40): +13.5dBm minimum ▪ 802.11ac MCS9(VHT80): +12.5dBm minimum ▪ 802.11ac MCS9(VHT160): +10.5dBm minimum ▪ 802.11ax MCS11(HE20) (6GHz): +11.5dBm minimum ▪ 802.11ax MCS11(HE40) (6GHz): +7.5dBm minimum ▪ 802.11ax MCS11(HE80) (6GHz): +7.5dBm minimum ▪ 802.11ax MCS11(HE160) (6GHz): +7.5dBm minimum

	▪ 802.11be MCS13(EHT20) (6GHz): 11.5dBm ▪ 802.11be MCS13(EHT40) (6GHz): 7.5dBm ▪ 802.11be MCS13(EHT80) (6GHz): 7.5dBm ▪ 802.11be MCS13(EHT160) (6GHz): 6.5dBm ▪ 802.11be MCS13(EHT320) (6GHz): 4.5dBm
Power Consumption	▪ Transmit mode 3.1 W ▪ Receive mode 1.8 W ▪ Idle mode (PSP) 180 mW (WLAN Associated) ▪ Idle mode 50 mW (WLAN unassociated) ▪ Connected Standby 10mW ▪ Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[2]	▪802.11b, 1Mbps: -93.5dBm maximum ▪802.11b, 11Mbps: -85dBm maximum ▪ 802.11a/g, 6Mbps: -90.5dBm maximum ▪ 802.11a/g, 54Mbps: -72.5dBm maximum ▪ 802.11n, MCS0(HT20): -90dBm maximum ▪ 802.11n, MCS7(HT20): -71.5dBm maximum ▪ 802.11n, MCS0(HT40): -88.5dBm maximum ▪ 802.11n, MCS7(HT40): -68.5dBm maximum ▪ 802.11ac, MCS9(VHT20): -88.5dBm maximum ▪ 802.11ac, MCS9(VHT40): -65.5dBm maximum ▪ 802.11ac, MCS9(VHT80): -60.5dBm maximum ▪ 802.11ac, MCS9(VHT160): -58.5dBm maximum ▪ 802.11ax, MCS11(HE20) (6GHz): -59.5dBm maximum ▪ 802.11ax, MCS11(HE40) (6GHz): -56.5dBm maximum ▪ 802.11ax, MCS11(HE80) (6GHz): -53.5dBm maximum ▪ 802.11ax, MCS11(HE160) (6GHz): -51.5dBm maximum ▪ 802.11be, MCS13(EHT20) (6GHz): -55.5dBm maximum ▪ 802.11be, MCS13(EHT40) (6GHz): -53.5dBm maximum ▪ 802.11be, MCS13(EHT80) (6GHz): -51.5dBm maximum ▪ 802.11be, MCS13(EHT160) (6GHz): -48.5dBm maximum ▪ 802.11be, MCS13(EHT320) (6GHz): -45.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity Two embedded tri-band 2.4/5/6 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm

Technical Specifications – Networking

Weight	1. Type 2230: 2.8g 2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 104° F (-10° to 40° C) Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Wireless Card Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class I Bluetooth device with a maximum transmit power of +15.5 dBm for BR and +13dBm for EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth® Software Supported Link Topology	1.Microsoft Windows Bluetooth Software 2.Linux/Chrome OS Bluetooth Software.
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Certifications	FCC (47 CFR) Part 15C/E, Section 15.247, 15.249, 15.407 ETSI 300 328, ETSI 301 893, ETSI 303 687
Bluetooth® Profiles Supported	Bluetooth 4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan Bluetooth 4.2 ESR08 Compliance LE Secure Connection- Basic/Full

	LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Bluetooth 5.2 ESR9/10 Compliance
	ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising
	2Mbps LE LE Long Range Bluetooth 5.3 Host to Controller Encryption Key Control Enahancements Compliance to the latest Errata Section 12.3 of Bluetooth 5.3 specification

1. Wi-Fi 7: Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires compatible Windows 11 OS, compatible processor, and separately purchased Wi-Fi 7 router to support backwards compatibility with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported. The specification for 802.11BE is a draft specification and is not final. If the final specification differs from the draft specification, it may affect the ability of the device to communicate with other 802.11BE devices..
2. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

MediaTek MT7925 Wi-Fi 7 + Bluetooth® 6.0 (802.11be 2x2)[1]	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11be IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k

Technical Specifications – Networking

	IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n/ax/be ▪ 2.402 – 2.482 GHz 802.11a/n/ac/ax/be ▪ 4.9 – 4.95 GHz (Japan) ▪ 5.15 – 5.25 GHz ▪ 5.25 – 5.35 GHz ▪ 5.47 – 5.725 GHz ▪ 5.825 – 5.850 GHz ▪ 5.955 – 6.415 GHz ▪ 6.435 – 6.515 GHz ▪ 6.535 – 6.875 GHz ▪ 6.895 – 7.115 GHz
Data Rates	▪ 802.11b: 1, 2, 5.5, 11 Mbps ▪ 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps ▪ 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps ▪ 802.11n: max 300Mbps ▪ 802.11ac: 1733Mbps ▪ 802.11ax: max 2.4Gbps ▪ 802.11be: max 2.8Gbps (160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM, 4096QAM
Security	▪ IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only ▪ AES-CCMP: 128 bit in hardware ▪ 802.1x authentication ▪ WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. ▪ WPA2 certification ▪ WPA3 certification ▪ IEEE 802.11i ▪ WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power	▪ 802.11b, 1Mbps: +17dBm minimum ▪ 802.11g, 6Mpbs: +16dBm minimum ▪ 802.11a, 6Mbps: +17dBm minimum ▪ 802.11n, MCS7(HT20): +14dBm minimum ▪ 802.11n, MCS7(HT40): +13.5dBm minimum ▪ 802.11ac MCS9(VHT20): 13.5dBm minimum

	▪ 802.11ac MCS9(VHT20): 13.5dBm minimum ▪ 802.11ac MCS9(VHT40): +13.5dBm minimum ▪ 802.11ac MCS9(VHT80): +12.5dBm minimum ▪ 802.11ac MCS9(VHT160): +10.5dBm minimum ▪ 802.11ax MCS11(HE20) (6GHz): +11.5dBm minimum ▪ 802.11ax MCS11(HE40) (6GHz): +7.5dBm minimum ▪ 802.11ax MCS11(HE80) (6GHz): +7.5dBm minimum ▪ 802.11ax MCS11(HE160) (6GHz): +7.5dBm minimum ▪ 802.11be MCS13(EHT20) (6GHz): +11.5dBm ▪ 802.11be MCS13(EHT40) (6GHz): +7.5dBm ▪ 802.11be MCS13(EHT80) (6GHz): +7.5dBm ▪ 802.11be MCS13(EHT160) (6GHz): +6.5dBm
Power Consumption	▪ Transmit mode 2.7 W ▪ Receive mode 1.8 W ▪ Idle mode (PSP) 180 mW (WLAN Associated) ▪ Idle mode 50 mW (WLAN unassociated) ▪ Connected Standby 10mW ▪ Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[2]	▪802.11b, 1Mbps: -93.5dBm maximum ▪802.11b, 11Mbps: -85dBm maximum ▪ 802.11a/g, 6Mbps: -90.5dBm maximum ▪ 802.11a/g, 54Mbps: -72.5dBm maximum ▪ 802.11n, MCS0(HT20): -90dBm maximum ▪ 802.11n, MCS7(HT20): -71.5dBm maximum ▪ 802.11n, MCS0(HT40): -88.5dBm maximum ▪ 802.11n, MCS7(HT40): -68.5dBm maximum ▪ 802.11ac, MCS9(VHT20): -88.5dBm maximum ▪ 802.11ac, MCS9(VHT40): -65.5dBm maximum ▪ 802.11ac, MCS9(VHT80): -60.5dBm maximum ▪ 802.11ac, MCS9(VHT160): -58.5dBm maximum ▪ 802.11ax, MCS11(HE20) (6GHz): -59.5dBm maximum ▪ 802.11ax, MCS11(HE40) (6GHz): -56.5dBm maximum ▪ 802.11ax, MCS11(HE80) (6GHz): -53.5dBm maximum ▪ 802.11ax, MCS11(HE160) (6GHz): -51.5dBm maximum ▪ 802.11be, MCS13(EHT160) (6GHz): -48.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity Two embedded tri-band 2.4/5/6 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm

Technical Specifications – Networking

Weight	1. Type 2230: 2.8g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 104° F (-10° to 40° C) Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4/6.0 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4/6.0 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class I Bluetooth device with a maximum transmit power of +15.5 dBm for BR and +13dBm for EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth® Software Supported Link Topology	1.Microsoft Windows Bluetooth Software 2.Linux/Chrome OS Bluetooth Software.
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth® Profiles Supported	Bluetooth 4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan

	Bluetooth 4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Bluetooth 5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range Bluetooth 5.3 Host to Controller Encryption Key Control Enhancements Compliance to the latest Errata Section 12.3 of BT 5.3 specification Bluetooth 5.4 Bluetooth 6.0

1. 1. Wi-Fi 7: Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires compatible Windows 11 OS, compatible processor, and separately purchased Wi-Fi 7 router to support backwards compatibility with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported. The specification for 802.11BE is a draft specification and is not final. If the final specification differs from the draft specification, it may affect the ability of the device to communicate with other 802.11BE devices.
2. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

AUDIO / MULTIMEDIA

High-Definition Audio

Type	Integrated
HD Stereo Codec	Realtek ALC3247-CG
Internal Speaker Amplifier	Codec integrated stereo Class-D Speaker Amplifier
Sampling	Speaker / Headphone: 16/24bit: 44.1/48kHz output Microphone / Headset Mic: 16bit, 44.1/48kHz input
Analog Audio	Yes
# of Channels on line-out	2 channel (through audio jack)
Internal speaker	Yes, stereo speaker output, 2W per channel
Microphone	Yes, stereo digital microphone input with Realtek proprietary Acoustic Echo Cancellation (AEC), Beam Forming (BF), and Noise Suppression (NS) technology, significantly improving voice quality for PC VoIP applications
Headphone	Yes, Combo audio jack supports stereo headphone and headset mic

Technical Specifications – Integrated Camera

CAMERA

NOTE: The Integrated webcam is a windows Hello Camera and IR is supported on 5MP Camera.
Optional integrated high-speed USB 2.0 compliant webcam 5MP resolution CMOS image sensor. The module integrates a USB 2.0 controller, color-processing engine and high-quality image to provide up to 30fps at 5MP size in high-speed mode.

Module Key Features	1/5", F2.0, 5MP, webcam for OS with build-in UVC driver
Automatic Image Control	Automatic Exposure Control Automatic White Balance Control Automatic Gain Control
Image Quality Control	Brightness, Contrast, Gamma, Hue, Saturation, Sharpness, Backlight Compensation, Anti-Flicker, White Balance, Image Flip, Night Mode, Digital Zoom, Roll and Exposure Controls.
Resolution Support	4:3 → 5Mp (2560x1920)
	16:9 → 5Mp (2560x1440), 1080p (1920x1080)
	720p (1280x720), 640x360
Power Saving Support	Suspend, Hibernation
On Board Component	White LED Indicator x1 IR LED x1

Performance	
Device Name	HP 5MP Camera
Brightness Control	-64~64 (0)
Contrast Control	0~64 (32)
Hue Control	-40~40 (0)
Saturation Control	0~128 (64)
Sharpness Control	0~5 (0)
Gamma Control	72~500 (100)
White Balance	2800~6500, auto (4000, auto)
Backlight	0~1 (0)
Exposure Control	-8~0, auto (-5,Auto)
Low light Compensation	Enable, Disable (Enable)
Anti-flicker (Power line)	50Hz, 60Hz (50Hz)
Format of Image Output Data	YUY2, MJPG

Technical Specifications – Power

POWER

Power Supply	100W EPS Wall Mount Type-C, active PFC, 88% average efficiency at 115V & 89% at 230Vac 280WSmart PFC Standard Barrel 7.4mm Straight C14 SR-S; 89% efficiency (advanced hub)
Operating Voltage Range	90V~264VAC
Rated Voltage Range	100V~240AC
Rated Line Frequency	50~60HZ
Operating Line Frequency Range	47~63HZ
Rated Input Current	100W≦1.6A，<2.4A RMS/280W
ENERGY STAR® Compliant	ENERGY STAR® certified configurations available and EPEAT registered *
Power Cord Length	2.0m

NOTE: Power supply meets ENERGY STAR® compliance in conjunction with a select range of processors and modules.
*Energy Star in under testing & in process of certification at the time this document is written.

Technical Specifications – Weights and Dimensions

WEIGHTS & DIMENSIONS

NOTE: Weight and dimensions below do not include CFDs.

Head Unit-15.6" Landscape+Stand+Stability Plate

Head Unit Dimmensions (HxWxD)	13 x 14.7 x 8.7 in 329.6 x 372.6 x 220 mm
Head Unit Volume	1648.51 cu in 27 L
Head Unit Weight	10.67 lb 4.84 kg

HP Engage One G2 Advanced Hub

Hub Dimmensions (HxWxD)	1.1 x 10.8 x 3.9 in 27 x 275 x 100 mm
Hub Weight	1.8 lb 0.8 kg

HP Engage One G2 VESA Mount

Mount Dimmensions (HxWxD)	0.7 x 5.1 x 4.7 in 18 x 130 x 120 mm
Mount Weight (Without adapter)	17.14 lb 0.31 kg

Engage One G2 Stand only

Stand Weight	5.2 lb 2.38 kg

Engage One G2 Swivel Stand with Stability Plate only

Swivel Stand Weight	6 lb 2.73 kg

System Summary Dimension Matrix

	Width (Horizontal) x Height (Vertical) x Thickness
15.6" Landscape Display Head only Dimmensions	372.6 x 233.6 x 17.5 mm
15.6" Landscape Display Head only Weight	2.45KG and 5.39 ibs

NOTE*: 23.8" Portrait can only be support with SLIM VESA mount, not configurable with any Column stand, not configurable with column hub.

Technical Specifications – Weights and Dimensions

	Width x Depth x Thickness
Stability Base only Dimmensions	305.3 x 220.3 x 21.7
Stability Base with Advanced Hub only Dimmensions	305.3 x 220.3 x 40.9

Advanced Hub with Stability Plate

Dimmensions	1.6 x 12 x 8.7 in 40.9 x 305.3 x 220.3 mm
Volume	167.87 cu in 2.8 L
Weight	6 lb 2.73 kg

Display + Stand (When working angle is 0 degrees)

Dimmensions	13 x 14.7 x 8.7 inch 329.6 x 372.6 x 220 mm
Volume	1648.51 cu in 10.67 L
Weight	0.67 ib 4.84 kg

Display+stand (when working angle is 60 degree)

Dimmensions	11.3 x 14.7 x 8.9 in 287.4 x 372.6 x 226 mm
Volume	1476.75 cu in 24.2 L
Weight	10.67 lb 4.84 kg

Landscape dimensions +Advanced Hub (when working angle is 60 degree)

Dimmensions	12.4 x 14.7 x 8.9 in 314.3 x 372.6 x 226 mm
Volume	1615.25 cu in 26.5 L
Weight	13.14 lb 5.96 kg

Technical Specifications – Weights and Dimensions

Display + Stand + Advanced Hub (when working angle is is 0 degreed

Dimmensions	14 x 14.7x 8.7 in 356.5 x 372.6 x 220 mm
Volume	1783.31 cu in 29.2 L
Weight	13.14 ib 5.96 kg

NOTE: HP Engage One Pro All-in-One System can only be supported in Landscape mode.

Technical Specifications – Magnetic Stripe Reader

MISCELLANEOUS FEATURES

Temperature, Humidity, Altitude

Temperature	**Operating**	50° to 104° F (10 to 40° C)
	Non-operating	-22° to 149° F (-30°to 65° C)
Humidity	**Operating**	20%-85% relative humidity at max inlet temperature
	Non Operating	20%-85% relative humidity at max inlet temperature
Shock	**Operating**	40g, six surfaces
	Non Operating	30g, six surfaces
Vibration	**Operating**	2-g peak acceleration
	Non Operating	3-g peak acceleration
Altitude (unpressurized)	**Operating**	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 30,000 ft (9,144 m)

General

Magnetic stripe formats	ISO 7811, AAMVA
Card Thickness	0.38 to 1.14 mm (0.015 to 0.045 in)
Indicators	Bi-colored LED, beeper (requires system audio driver)
Card Speed	3 to 75 ips (7.6 to 190.5 cm/s)

Mechanical

Weight	5.67 g
Slot width	1.14 mm (0.045 in)

Connection

Interface	Eight-pin male Molex 51021-0800
Cable Length	125 ± 6.4 mm

Power

Power Supply	3.0 to 3.6 VDC
I/O Voltage Range	2.7 to 3.6 VDC
Active Power Supply Current	5
mA Standby Power Supply Current	0.03 mA

Technical Specifications – Magnetic Stripe Reader

Temperature Range

Operating	0°C to 40°C
Relative Humidity	-10% to 90% non-condensing

Reliability

Operating Life	1,000,000 card swipes minimum

Agency Certifications

FCC, CE, USB-IF

Kit Contents

HP Engage One Pro Magnetic Stripe Reader, documentation, warranty card.

ENVIRONMENTAL & INDUSTRY

Environmental Data

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR® certified configurations available
- EPEAT Gold with Climate+ registered configurations available. See http://www.epeat.net for registration status and tier levels by country.

* Based on US EPEAT registration according to EPEAT criteria and EPEAT Climate+, status and tier level varies by country. Visit http://www.epeat.net for more information.

Sustainable Impact Specifications

- 75% post-consumer recycled plastic[4]
- Low halogen[1]
- Ocean-Bound Plastic in speaker enclosure[2]
- 25% ITE-derived closed loop plastic[6]

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Engage One Pro model is based on a typically configured system featuring an SSD, a high efficiency power supply, and a Microsoft Windows® operating system.

HP Engage One G2 AiO System Model 15.6”

Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)	9.83W	9.62W	9.82W
Normal Operation (Long idle)	2.47W	2.46W	2.46W
Sleep	2.47W	2.46W	2.46W
Off	0.95W	0.95W	0.96W
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)	33.54 BTU/hr	32.82 BTU/hr	33.51 BTU/hr
Normal Operation (Long idle)	8.43 BTU/hr	8.19 BTU/hr	8.19 BTU/hr
Sleep	8.43 BTU/hr	8.19 BTU/hr	8.19 BTU/hr
Off	3.24 BTU/hr	3.24 BTU/hr	3.28 BTU/hr

* Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour

Technical Specifications – Environmental & Industry

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)
Typically Configured – Idle	2.6	16.7
Fixed Disk – Random writes	2.6	16.7

NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 2 memory slots
- M.2 2230 slot for WLAN
- (1) M.2 2280 slot for SSD

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC
Batteries used in the product do not contain:
Mercury greater the1ppm by weight
Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)
Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is registered as EPEAT Gold and has attained EPEAT Climate+ in the US, status and tier level varies by country. See http://www.epeat.net.
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 75% post-consumer recycled plastics (by wt.)
- This product is 96% recycle-able when properly disposed of at end of life.

Packaging Materials

External: PAPER/Corrugated

Internal: PLASTIC/Polyethylene Expanded – EPE

PLASTIC/Polyethylene low density – LDPE

The EPE foam packaging material is made from 100% recycled content.

The corrugated paper packaging materials contains at least 35% recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

NOTES: * EPE foam packaging material is considered "recycled" pre-Consumer. The scrap or waste EPE material from the manufacturing process of these EPE foam pieces are re-introduced into the manufacturing process.

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP Inc. web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment

Global Citizenship Report
http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications
http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:
PC Product Design ISO 14001 certificate

and
HP Operations ISO 14001 certificate

Footnotes

1.External power supplies, WWAN modules, power cords, cables and peripherals excluded. Service parts obtained after purchase may not be Low Halogen.

2.Recycled plastic content percentage is based on the definition set in EPEAT criteria.

AFTER MARKET OPTIONS in MSPecs

AMO Part No.	Description
CU6T0AA	HP Engage One G2 VESA Mount
CU6T6AA	HP 1.8m USB-C VESA to Adv Hub Cbl
D9LM8AA	HP Engage One G2 Advanced Hub
9YH43AA	Engage One Pro U-shaped Adapter
CU6T2AA	HP 0.45m USB-C Head to Att Adv Hub Cbl
CU6T3AA	HP 1.8m USB-C Head to DIB Adv Hub Cbl
CU9U5AA	HP Engage One G2 2x20 CFD Ring
CU6T4AA	HP 0.45m USB-A 2x20 CFD Att Adv Hub Cbl
CU6T5AA	Cbl HP 1.8m USB-A 2x20 CFD to DIB AdvHub
CU9U6AA	HP Engage One G2 10-inch CFD Ring
CJ3C5AA	HP 0.62m USB-C 10-inch CFD to Advanced Hub Cable
2WY48AA	Engage 10-IN Display Vesa Plate [1]
C3QT0AA	HP Engage 10t Tap + Scan Display [1]
C3QT1AA	HP Engage 10t Tap Display [1]
C3QT2AA	HP Engage 10 Touch Display [1]
C3QT3AA	HP Engage 10 Display [1]
2W7M4AA	Engage One Pro Flexible Pole Single Mount
2W7M3AA	Engage One Pro Flexible Back-to-Back Bracket

1. CFD comes with 1.8m USB-C cable

Compatibility

The HP Engage One Magnetic Stripe Reader is compatible with the HP Engage One G2 All-in-One System.

NOTE: Not all Point of Sale system models are available in all regions.

Warranty

Three (3) year limited warranty with advance exchange when purchased from HP.

SERVICE AND SUPPORT

Ninety-day (90-90-90), one-year (1-1-1), and three-year (3-3-3) limited warranty[1] delivers (ninety days/one year/three years) of on-site, next business day[2] service for parts and labor and complimentary limited technical support. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://http://www.hp.com/go/cpc.[3]

1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
3. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Change Log

SUMMARY OF CHANGES

Date of change	Version History	Action	Description of changes
July 18, 2026	From v1 to v2	Update	Ports section updated, headers corrected and fan lees removed
July 22, 2026	From v2 to v3	Update	Operator Display, Storage, Networking, Magnetic Stripe Reader, *AMO* & all Headers
July 27, 2026	From v3 to v4	Updated	Weights and Dimensions Section